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Our File: MIT/10523

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**APPLICANT:** Lee et al. **GROUP:** 2871

**SERIAL NO:** 10/043,896 **EXAMINER:** G.Y. Wang

**FILED:** January 9, 2002

**FOR:** HIGH DENSITY INTEGRATED OPTICAL CHIP

**Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450**

Sir:

**AMENDMENT**

In response to the Office Action mailed June 7, 2005, please amend the above-identified application as follows: